



#9/B
Attorney Docket No. 566.39636X00
Serial No. 09/762,823
5/28/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): WATANABE, et al.

Group: 2827

Serial No.: 09/762,823

Examiner: Cuneo, Kamand

Filed: April 23, 2001

For: ADHESIVE FOR BONDING CIRCUIT MEMBERS, CIRCUIT BOARD
AND PROCESS FOR ITS PRODUCTION

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

May 20, 2002

Sir:

In response to the Office Action mailed February 20, 2002, please amend the
above-identified application as follows:

IN THE CLAIMS:

Please amend the claims presently in the application as follows:

31
1. (Twice Amended) An adhesive for bonding circuit members which is to be
put between circuit electrodes facing each other;

said circuit electrodes facing each other being pressed interposing the
adhesive between them, to interconnect the electrodes electrically in the direction of
pressing;

said adhesive comprising a first adhesive layer which includes an adhesive
resin composition and an insulative inorganic filler;

05/21/2002 ZJUHAR1 00000053 09762823

02 FC:103

18.00 OP

1

RECEIVED
MAY 23 2002
TC 2800 MAIL ROOM